

SOT923-2

plastic thermal enhanced very thin quad flat package; no leads; 64 terminals; body 9 x 9 x 0.85 mm

8 February 2016

Package information

1. Package summary

Terminal position code	Q (quad)
Package type descriptive code	HVQFN64
Package type industry code	HVQFN64
Package style descriptive code	HVQFN (thermal enhanced very thin quad flatpack; no leads)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	26-3-2008

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	8.9	-	9	9.1	mm
E	package width	8.9	-	9	9.1	mm
A	seated height	0.85	-	0.9	1	mm
A ₂	package height	[tbd]	-	0.85	[tbd]	mm
n ₂	actual quantity of termination	-	-	64	-	

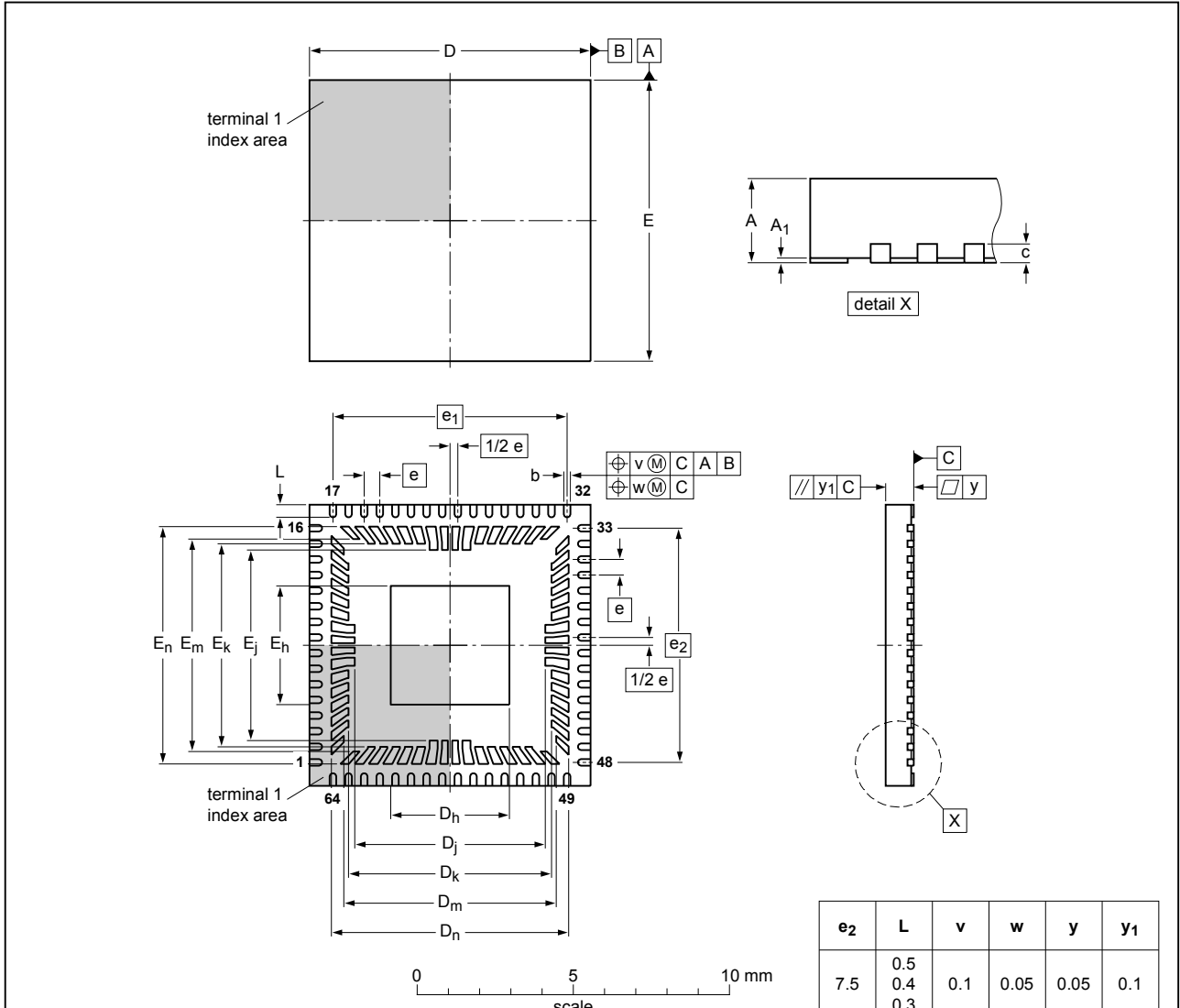


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2. Package outline

HVQFN64: plastic thermal enhanced very thin quad flat package; no leads; 64 terminals; body 9 x 9 x 0.85 mm

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e ₂	L	v	w	y	y ₁
7.5	0.5	0.1	0.05	0.05	0.1
	0.4				
	0.3				

DIMENSIONS (mm are the original dimensions)

UNIT	A	A ₁	b	c	D ⁽¹⁾	D _h	D _j	D _k	D _m	D _n	E ⁽¹⁾	E _h	E _j	E _k	E _m	E _n	e	e ₁	
mm	max	1.00	0.05	0.30		9.1	3.95	6.2	6.6	6.9	7.7	9.1	3.95	6.2	6.6	6.9	7.7		7.5
	nom	0.90	0.02	0.21	0.2	9.0	3.80	6.1	6.5	6.8	7.6	9.0	3.80	6.1	6.5	6.8	7.6	0.5	
	min	0.85	0.00	0.18		8.9	3.65	6.0	6.4	6.7	7.5	8.9	3.65	6.0	6.4	6.7	7.5		

Notes

1. Plastic or metal protrusions of 0.075 mm maximum per side are not included.
2. Mold flash on exposed inner terminal is allowed.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT923-2	---	---	---			08-03-10 08-03-26

Fig. 1. Package outline HVQFN64 (SOT923-2)

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3. Legal information

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